503909934 07/11/2016

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1 Stylesheet Version v1.2 EPAS ID: PAT3956586

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
KUN-PING HUANG	06/22/2016
YU-WEN CHI	06/22/2016

RECEIVING PARTY DATA

Name:	INDUSTRIAL TECHNOLOGY RESEARCH INSTITUTE	
Street Address:	NO. 195, SEC. 4, CHUNG HSING RD., CHUTUNG,	
City:	HSINCHU	
State/Country:	TAIWAN	
Postal Code:	31040	

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	15202582

CORRESPONDENCE DATA

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Correspondent Name: JIANQ CHYUN INTELLECTUAL PROPERTY OFFICE

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ATTORNEY DOCKET NUMBER:	61064-US-PA
NAME OF SUBMITTER:	BELINDA LEE
SIGNATURE:	/Belinda Lee/
DATE SIGNED:	07/11/2016

Total Attachments: 2

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PATENT 503909934 REEL: 039127 FRAME: 0212

P53040060US 61064-US-PA

ASSIGNMENT

WHEREAS.

1. Kun-Ping Huang

2. Yu-Wen Chi

hereinafter referred to as ASSIGNOR, has/have invented certain new and useful improvements as described and set forth in the below identified application for United States Letters Patent:

Title: METAL-DOPED GRAPHENE AND GROWTH METHOD OF THE SAME

[] Filed:

Serial No.

[x] Executed concurrently with the execution of this instrument

WHEREAS 1. Industrial Technology Research Institute

of No. 195, Sec. 4, Chung Hsing Rd., Chutung, Hsinchu 31040, Taiwan, R. O. C.

hereinafter referred to as ASSIGNEE, is desirous of acquiring ASSIGNOR'S interest in the said invention and application and in any U.S. Letters Patent which may be granted on the same:

NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN: Be it known that, for good and valuable consideration, receipt of which is hereby acknowledged by Assignor, Assignor has/have sold, assigned and transferred, and by these presents does/do sell, assign and transfer unto the said Assignee, and Assignee's successors and assigns, all his/her/their rights, title and interest in and to the said invention and application and all future improvements thereon, and in and to any Letters Patent which may hereafter be granted on the same in the United States, the said rights, title and interest to be held and enjoyed by said Assignee as fully and exclusively as it would have been held and enjoyed by said Assignor had this Assignment and transfer not been made, to the full end and term of any Letters Patent which may be granted thereon, or of any division, renewal, continuation in whole or in part, substitution, conversion, reissue, prolongation or extension thereof.

Assigner further agrees/agree that he/she/they will, without charge to said Assignee, but at Assignee's expense, cooperate with Assignee in the prosecution of said application and/or applications, execute, verify, acknowledge and deliver all such further papers, including applications for Letters Patent and for the reissue thereof, and instruments of assignment and transfer thereof, and will perform such other acts as Assignee Lawfully may request, to obtain or maintain Letters Patent for said invention and improvement, and to vest title thereto in said Assignee, or Assignee's successors and assigns.

PATENT REEL: 039127 FRAME: 0213

RECORDED: 07/11/2016

Second Joint Inventor (if any): Yu-Wen Chi

ASSIGNMENT CONTINUED

IN TESTIMONY WHEREOF, Assignor has/have signed his/her/their name(s) on the date(s)

Signature: Kun-Ping Huang

Date: June 32 fh, 20(6)

Sole or First Joint Inventor: Kun-Ping Huang

Signature: Yu - Wen, Ch. T. Date: June 32 fh, 20(6)